

REV.	DESCRIPTION	DATE
A/0	新版发行	2016.11.28

技术要求:

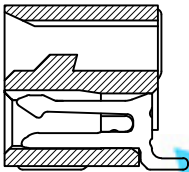
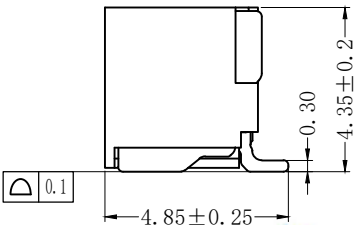
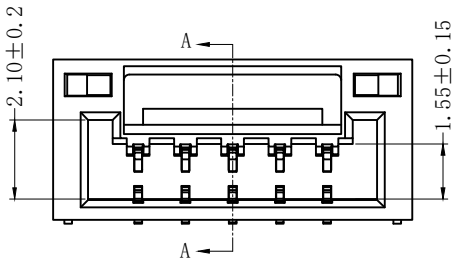
- 1、塑件材料: LCP (UL-94V-0)
- 2、接触件: 磷青铜镀锡
- 3、接触电阻: $\leq 20\text{m}\Omega$
- 4、绝缘电阻: $\geq 100\text{M}\Omega$
- 5、额定电压: 50V AC DC
- 6、额定电流: 1.0A AC DC
- 7、耐压: 能承受500V AC/Min ute
- 8、工作温度: $-25^{\circ}\sim +105^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 260^{+5}_{-0} , 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

GH-1.25-XP-WT

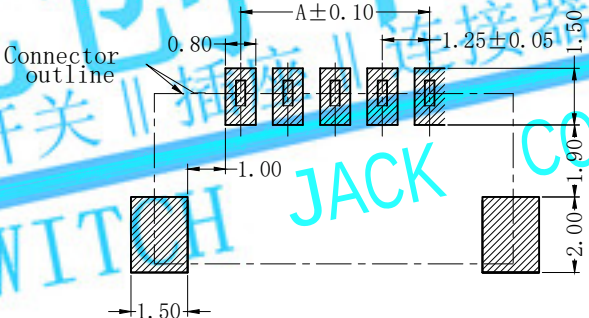
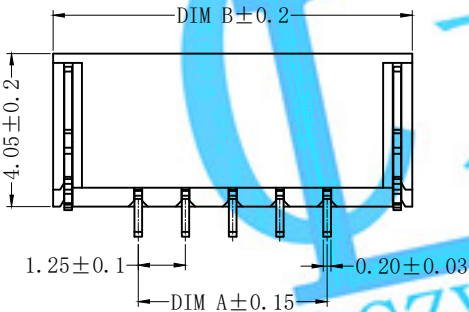
Circuits	Dimensions (mm)	
	A	B
02	1.25	5.75
03	2.50	7.00
04	3.75	8.25
05	5.00	9.50
06	6.25	10.75
07	7.50	12.00
08	8.75	13.25
09	10.00	14.50
10	11.25	15.75
11	12.50	17.00
12	13.75	18.25
13	15.00	19.50
...	...	...
20	23.75	28.25

3	焊片 Fitting Nail	磷青铜 Phosphor Bronze	2	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN.
2	端子 Contact	磷青铜 Phosphor Bronze	n*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN.
1	基座 Wafer	LCP (UL94V-0)	1	本色
序号	名称	材料	数量	附注

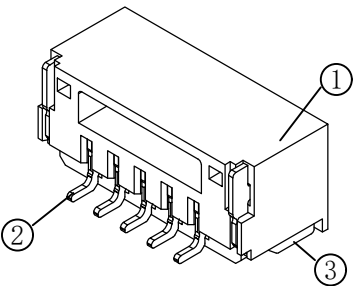
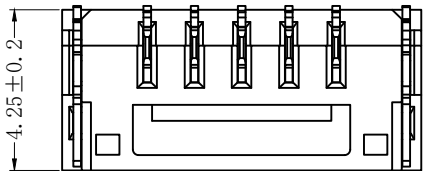
GENERAL TOLERANCES				DRAWN BY		龙创中业电子科技(东莞)有限公司	
0.X	±0.25	X°	±3°	CHK. BY			
0.XX	±0.12						
0.XXX	±0.05	X.X°	±0.5°	APRV. BY			
UNIT	SIZE	SCALE		DRAWING NO.		1 OF 1	PART NO. GH-1.25-XP-WT
MM	A4	1:1		006-0082-001		TITLE	
					2.00 FPC CONN. ZIF SMT FRONTFLIP H=2.0 DOUBLE LOWER CONTACT		



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



借用登记

旧底图总号

底图总号

签字

日期